

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.12212	100.0	7.3
			<b>Subtotal</b>	<b>0.12212</b>	<b>100</b>	<b>7.3</b>
Post-plating	Lead alloy	Tin (Sn)	7440-31-5	0.45501	100.0	27.2
			<b>Subtotal</b>	<b>0.45501</b>	<b>100</b>	<b>27.2</b>
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02008	0.03	1.20057
	Copper alloy	Iron (Fe)	7439-89-6	0.06694	0.1	4.0019
	Copper alloy	Copper (Cu)	7440-50-8	66.85733	99.87	3,996.69753
			<b>Subtotal</b>	<b>66.94435</b>	<b>100</b>	<b>NaN</b>
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.09702	6.5	125.359
	Polymer	Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic)	29690-82-2	5.1619	16.0	308.576
	Filler	Silica fused	60676-86-0	22.90595	71.0	1,369.306
	Flame retardant	Metal hydroxide		2.09702	6.5	125.359
			<b>Subtotal</b>	<b>32.26189</b>	<b>100</b>	<b>NaN</b>
Solder Wire	Lead alloy	Tin (Sn)	7440-31-5	0.0033	5.0	0.1975
	Lead alloy	Silver (Ag)	7440-22-4	0.00165	2.5	0.09875
	Lead alloy	Lead (Pb)	7439-92-1	0.06112	92.5	3.65375
			<b>Subtotal</b>	<b>0.06607</b>	<b>100</b>	<b>3.95</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.15055	100.0	9
			<b>Subtotal</b>	<b>0.15055</b>	<b>100</b>	<b>9</b>
			<b>Total</b>	<b>99.99999</b>	<b>100</b>	<b>NaN</b>

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